



Product Change Notification / JAON-26MATN756

Date:

28-Sep-2022

Product Category:

8-bit Microcontrollers, Analog Temperature Sensors, Battery Management and Fuel Gauges - Battery Chargers, Capacitive Touch Sensors, Digital Potentiometers, Digital Temperature Sensors, Linear Op Amps, Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5297 and 5297.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 93LCxxx, 93AAxxx, 93Cxxx, PIC10F2xx, 25LC0xxx, 25AA0xxx, MTCH101, 24VL0xx, 24LC0xx, 24AA0xxx, 24C01C, 34VL02, 34LC02, 34AA02, MCP40xx, MCP9800xx, MCP9802xx, MCP738xx, MCP950xx, MCP6Vxxx, and MCP64xx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

Affected CPNs:

[JAON-26MATN756_Affected_CPN_09282022.pdf](#)
[JAON-26MATN756_Affected_CPN_09282022.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 93LCxxx, 93AAxxx, 93Cxxx, PIC10F2xx, 25LC0xxx, 25AA0xxx, MTCH101, 24VL0xx, 24LC0xx, 24AA0xxx, 24C01C, 34VL02, 34LC02, 34AA02, MCP40xx, MCP9800xx, MCP9802xx,

MCP738xx, MCP950xx, MCP6Vxxx, and MCP64xx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	8900NC	8900NC
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:November 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	September 2022					>	November 2022				
Workweek	3 6	3 7	3 8	3 9	4 0		45	46	47	48	49
Initial PCN Issue Date					X						

Qual Report Availability										X		
Final PCN Issue Date										X		

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:September 28, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-26MATN756_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

JAON-26MATN756 - CCB 5297 and 5297.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 93LCxxx, 93AAxxx, 93Cxxx, PIC10F2xx, 25LC0xxx, 25AA0xxx, MTCH101, 24VL0xx, 24LC0xx, 24AA0xxx, 24C01C, 34VL02, 34LC02, 34AA02, MCP40xx, MCP9800xx, MCP9802xx, MCP738xx, MCP950xx, MCP6Vxxx, and MCP64xx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

93LC46AT-I/OT
93AA46AT-I/OT
93AA46AE48T-I/OT
93LC46AT-E/OT
93LC46BT-I/OT
93AA46BT-I/OT
93LC46BT-E/OT
93C46BT-I/OT
93C46BT-E/OT
93C46AT-I/OT
93C46AT-E/OT
93LC56AT-I/OT
93AA56AT-I/OT
93LC56BT-I/OT
93AA56BT-I/OT
93LC56AT-E/OT
93LC56BT-E/OT
93LC66AT-I/OT
93AA66AT-I/OT
93LC66BT-I/OT
93AA66BT-I/OT
93LC66AT-E/OT
93LC66BT-E/OT
93C56AT-I/OT
93C56BT-I/OT
93C56AT-E/OT
93C56BT-E/OT
93C66AT-I/OT
93C66BT-I/OT
93C66AT-E/OT
93C66BT-E/OT
93LC76AT-I/OT
93AA76AT-I/OT
93LC76BT-I/OT
93AA76BT-I/OT
93LC76AT-E/OT
93LC76BT-E/OT
93LC86AT-I/OT
93AA86AT-I/OT
93LC86BT-I/OT
93AA86BT-I/OT
93LC86AT-E/OT
93LC86BT-E/OT
93C76AT-I/OT
93C76BT-I/OT
93C76AT-E/OT

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93C86BT-I/OT
93C86AT-E/OT
93C86BT-E/OT
PIC10F200-E/OT
PIC10F200-I/OT215
PIC10F200-I/OT220
PIC10F200-I/OT223
PIC10F200-I/OT
PIC10F200T-I/OT071
PIC10F200T-I/OT102
PIC10F200T-I/OT108
PIC10F200T-I/OT119
PIC10F200T-I/OT125
PIC10F200T-I/OT128
PIC10F200T-I/OT131
PIC10F200T-I/OT151
PIC10F200T-I/OT153
PIC10F200T-I/OT163
PIC10F200T-I/OT169
PIC10F200T-I/OT177
PIC10F200T-I/OT182
PIC10F200T-I/OT185
PIC10F200T-I/OT190
PIC10F200T-I/OT192
PIC10F200T-I/OT194
PIC10F200T-I/OT195
PIC10F200T-I/OT196
PIC10F200T-I/OT200
PIC10F200T-I/OT202
PIC10F200T-I/OT208
PIC10F200T-I/OT209
PIC10F200T-I/OT212
PIC10F200T-I/OT215
PIC10F200T-I/OT216
PIC10F200T-I/OT217
PIC10F200T-I/OT219
PIC10F200T-I/OT220
PIC10F200T-I/OT221
PIC10F200T-I/OT222
PIC10F200T-I/OT223
PIC10F200T-I/OT224
PIC10F200T-I/OT225
PIC10F200T-I/OT226
PIC10F200T-I/OT
PIC10F200T-E/OT030
PIC10F200T-E/OT147
PIC10F200T-E/OT186

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PIC10F200T-E/OT
PIC10F202-E/OT
PIC10F202-I/OT
PIC10F202T-I/OT065
PIC10F202T-I/OT085
PIC10F202T-I/OT105
PIC10F202T-I/OT108
PIC10F202T-I/OT112
PIC10F202T-I/OT
PIC10F202T-E/OT081
PIC10F202T-E/OT096
PIC10F202T-E/OT109
PIC10F202T-E/OT
PIC10F204-E/OT
PIC10F204-I/OT
PIC10F204T-I/OT043
PIC10F204T-I/OT051
PIC10F204T-I/OT053
PIC10F204T-I/OT054
PIC10F204T-I/OT
PIC10F204T-E/OT028
PIC10F204T-E/OT038
PIC10F204T-E/OT050
PIC10F204T-E/OT
PIC10F206-E/OT
PIC10F206-I/OT
PIC10F206T-I/OT030
PIC10F206T-I/OT031
PIC10F206T-I/OT032
PIC10F206T-I/OT041
PIC10F206T-I/OT043
PIC10F206T-I/OT
PIC10F206T-E/OT
25LC010AT-I/OT
25AA010AT-I/OT
25LC010AT-E/OT
25LC020AT-I/OT
25AA020AT-I/OT
25AA02E48T-I/OT
25AA02E64T-I/OT
25AA02UIDT-I/OT
25LC020AT-E/OT
25LC040AT-I/OT
25AA040AT-I/OT
25LC040AT-E/OT
PIC10F220-E/OT
PIC10F220-I/OT

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PIC10F220T-I/OT035
PIC10F220T-I/OT037
PIC10F220T-I/OT040
PIC10F220T-I/OT
PIC10F220T-E/OT030
PIC10F220T-E/OT
PIC10F222-E/OT
MTCH101-I/OT
PIC10F222-I/OT
PIC10F222T-I/OT020
PIC10F222T-I/OT032
PIC10F222T-I/OT033
PIC10F222T-I/OT039
PIC10F222T-I/OT044
PIC10F222T-I/OT045
MTCH101T-I/OT
PIC10F222T-I/OT053
PIC10F222T-I/OT055
PIC10F222T-I/OT056
PIC10F222T-I/OT057
PIC10F222T-I/OT058
PIC10F222T-I/OT059
PIC10F222T-I/OT062
PIC10F222T-I/OT
PIC10F222T-E/OT
24VL025T/OT
24LC025T-I/OT
24AA025T-I/OT
24LC025T-E/OT
24VL014T/OT
24LC014T-I/OT
24AA014T-I/OT
24LC014T-E/OT
24C01CT-I/OT
24C01CT-E/OT
24AA025E48T-I/OT
24AA025E64T-I/OT
24AA025UIDT-I/OT
24AA025E48T-E/OT
24AA025E64T-E/OT
34VL02T/OT
34LC02T-I/OT
34AA02T-I/OT
34LC02T-E/OT
34AA02T-E/OT
MCP4024T-202E/OT
MCP4024T-502E/OT

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MCP4014T-202E/OT
MCP4014T-502E/OT
MCP4014T-103E/OT
MCP4014T-503E/OT
MCP9800A0T-M/OT
MCP9800A1T-M/OT
MCP9800A2T-M/OT
MCP9800A3T-M/OT
MCP9800A4T-M/OT
MCP9800A5T-M/OT
MCP9800A6T-M/OT
MCP9800A7T-M/OT
MCP9802A0T-M/OT
MCP9802A1T-M/OT
MCP9802A2T-M/OT
MCP9802A3T-M/OT
MCP9802A4T-M/OT
MCP9802A5T-M/OT
MCP9802A6T-M/OT
MCP9802A7T-M/OT
MCP73831T-2ACI/OT
MCP73831T-2ADI/OT
MCP73831T-2ATI/OT
MCP73831T-2DCI/OT
MCP73831T-3ACI/OT
MCP73831T-4ADI/OT
MCP73831T-5ACI/OT
MCP73831T-2ACI/OTAAA
MCP73832T-2ACI/OT
MCP73832T-2ATI/OT
MCP73832T-2DCI/OT
MCP73832T-2DFI/OT
MCP73832T-3ACI/OT
MCP73832T-4ADI/OT
MCP73832T-5ACI/OT
MCP73811T-420I/OT
MCP73811T-435I/OT
MCP73811T-440I/OT
MCP73811T-450I/OT
MCP73812T-420I/OT
MCP73812T-435I/OT
MCP73812T-440I/OT
MCP73812T-450I/OT
MCP9509CT-E/OT
MCP9509HT-E/OT
MCP9501PT-005E/OT
MCP9501PT-015E/OT

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MCP9501PT-045E/OT
MCP9501PT-055E/OT
MCP9501PT-065E/OT
MCP9501PT-075E/OT
MCP9501PT-085E/OT
MCP9501PT-095E/OT
MCP9501PT-105E/OT
MCP9501PT-115E/OT
MCP9501PT-125E/OT
MCP9501PT-135E/OT
MCP9501PT-145E/OT
MCP9503NT-005E/OT
MCP9503NT-015E/OT
MCP9503NT-025E/OT
MCP9503NT-035E/OT
MCP9503NT-045E/OT
MCP9503NT-055E/OT
MCP9503PT-005E/OT
MCP9503PT-015E/OT
MCP9503PT-025E/OT
MCP9502PT-055E/OT
MCP9502PT-005E/OT
MCP9502PT-015E/OT
MCP9502PT-025E/OT
MCP9502PT-035E/OT
MCP9502PT-045E/OT
MCP9502PT-065E/OT
MCP9502PT-075E/OT
MCP9502PT-085E/OT
MCP9502PT-095E/OT
MCP9502PT-105E/OT
MCP9502PT-115E/OT
MCP9502PT-125E/OT
MCP9502PT-135E/OT
MCP9502PT-145E/OT
MCP9504NT-005E/OT
MCP9504NT-015E/OT
MCP9504NT-025E/OT
MCP9504NT-035E/OT
MCP9504NT-045E/OT
MCP9504NT-055E/OT
MCP9504PT-005E/OT
MCP9504PT-015E/OT
MCP9504PT-025E/OT
MCP6V11T-E/OT
MCP6V11UT-E/OT
MCP6V16T-E/OT

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MCP6V31UT-E/OT
MCP6V36T-E/OT
MCP6V36UT-E/OT
MCP6471T-E/OT
MCP6481T-E/OT
MCP6491T-E/OT
MCP6421T-E/OT
MCP6V61T-E/OT
MCP6V61UT-E/OT
MCP6V66T-E/OT
MCP6V66UT-E/OT
MCP6V71T-E/OT
MCP6V71UT-E/OT
MCP6V76T-E/OT
MCP6V76UT-E/OT
MCP6V81T-E/OT
MCP6V81UT-E/OT
MCP6V86T-E/OT
MCP6V86UT-E/OT
MCP6V91T-E/OT
MCP6V91UT-E/OT
MCP6V96T-E/OT
MCP6V96UT-E/OT



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QUALIFICATION PLAN SUMMARY

PCN #: JAON-26MATN756

Date:

September 15, 2022

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 93LCxxx, 93AAxxx, 93Cxxx, PIC10F2xx, 25LC0xxx, 25AA0xxx, MTCH101, 24VL0xx, 24LC0xx, 24AA0xxx, 24C01C, 34VL02, 34LC02, and 34AA02 device families available in 6L SOT-23 package assembled at MMT assembly site. The qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP40xx, MCP9800xx, MCP9802xx, MCP738xx, MCP950xx, MCP6Vxxx, and MCP64xx device families available in 5L SOT-23 package will qualify by similarity (QBS).

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected 93LCxxx, 93AAxxx, 93Cxxx, PIC10F2xx, 25LC0xxx, 25AA0xxx, MTCH101, 24VL0xx, 24LC0xx, 24AA0xxx, 24C01C, 34VL02, 34LC02, and 34AA02 device families available in 6L SOT-23 package assembled at MMT assembly site. The qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP40xx, MCP9800xx, MCP9802xx, MCP738xx, MCP950xx, MCP6Vxxx, and MCP64xx device families available in 5L SOT-23 package will qualify by similarity (QBS).

CCB No.: 5297 and 5297.001

Misc.	Assembly site	MMT
	BD Number	BD-000738/01
	MP Code (MPC)	DECA14C8XAXF
	Part Number (CPN)	PIC10F220-E/OT
	MSL information	MSL-1@260C
	Assembly Shipping Media (T/R, Tube/Tray)	TnR
	Base Quantity Multiple (BQM)	3000
Lead-Frame	Paddle size	72x41 mils
	Material	CDA194
	DAP Surface Prep	Ag Spot Plated
	Treatment	No
	Process	Stamped
	Lead-lock	No
	Part Number	10100602
	Lead Plating	Matte Tin
	Strip Size	228.288x50.800mm
	Strip Density	192units/strip
Bond Wire	Material	CuPdAu
Die Attach	Part Number	8900NC
	Conductive	No
MC	Part Number	G600V
PKG	PKG Type	SOT-23
	Pin/Ball Count	6

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15		5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MMT/ MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL-1/260C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	JESD22-A118 +130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.